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November 2013

FDB2614

N-Channel PowerTrench® MOSFET 200 V, 62 A, 27 m Ω

Features

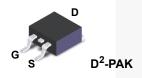
- $R_{DS(on)}$ = 22.9 $m\Omega$ (Typ.)@ V_{GS} = 10 V, I_D = 31 A
- High Performance Trench technology for Extremely Low $R_{DS(\text{on})}$
- · Low Gate Charge
- · High Power and Current Handing Capability

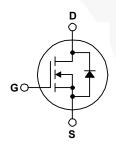
General Description

This N-Channel MOSFET is producedusing Fairchild Semiconductor's advanced PowerTrench® process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

Applications

- · Synchronous Rectification
- · Battery Protection Circuit
- · Motor Drives and Uninterruptible Power Supplies





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol		Parameter		FDB2614	Unit
V _{DS}	Drain-Source Voltage			200	V
V _{GS}	Gate-Source Voltage			± 30	V
I _D	Drain Current - Continuous (T _C = 25°C) - Continuous (T _C = 100°C))	62 39.3	A A
I _{DM}	Drain Current	- Pulsed	(Note 1)	see Figure 9	A
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		(Note 2)	145	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		(Note 3)	4.5	V/ns
P_D	Power Dissipation (T _C = 25°C) - Derate above 25°C		260 2.1		W W/°C
T _{J,} T _{STG}	Operating and Storage Temperature Range			-55 to +150	°C
T _L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		se,	300	°C

Thermal Characteristics

Symbol	Parameter	FDB2614	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.48	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (minimum pad of 2 oz copper), Max.	62.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (1 in ² pad of 2 oz copper), Max.	40	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB2614	FDB2614	D ² -PAK	330 mm	24 mm	800 units

Electrical Characteristics T_C = 25°C unless otherwise noted

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Off Charac	teristics			II.		
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V$, $I_D = 250\mu A$, $T_J = 25^{\circ}C$	200			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250μA, Referenced to 25°C		0.2		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 200V, V _{GS} = 0V V _{DS} = 200V, V _{GS} = 0V, T _J = 125°C		 	1 500	μ Α μ Α
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30V, V _{DS} = 0V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30V$, $V_{DS} = 0V$			-100	nA
On Charac	teristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0	4.0	5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	Static Drain-Source On-Resistance $V_{GS} = 10V, I_D = 31A$		22.9	27	mΩ
9 _{FS}	Forward Transconductance $V_{DS} = 10V, I_D = 31A$			72		S
Dynamic C	haracteristics					
C _{iss}	Input Capacitance		\	5435	7230	pF
C _{oss}	Output Capacitance	$V_{DS} = 25V, V_{GS} = 0V$ f = 1.0MHz	-	505	675	pF
C _{rss}	Reverse Transfer Capacitance	- 1 - 1.0ivii iz		110	165	pF
Switching	Characteristics				_	
t _{d(on)}	Turn-On Delay Time			77	165	ns
t _r	Turn-On Rise Time	$V_{DD} = 100V, I_{D} = 62A$ $V_{GS} = 10V, R_{GEN} = 25\Omega$	-	284	560	ns
t _{d(off)}	Turn-Off Delay Time	3-3	-	103	220	ns
t _f	Turn-Off Fall Time	(Note 4)		162	335	ns
Qg	Total Gate Charge		/	76	99	nC
Q_{gs}	Gate-Source Charge	$V_{DS} = 100V, I_D = 62A$ $V_{GS} = 10V$	/	35		nC
Q_{gd}	Gate-Drain Charge	(Note 4)		18		nC
Drain-Sour	ce Diode Characteristics and Maximum	n Ratings	1			
I _S	Maximum Continuous Drain-Source Diode Forward Current				62	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				186	Α
V_{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0V, I _S = 62A			1.2	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _S = 62A		145		ns
Q _{rr}	Reverse Recovery Charge	dI _F /dt =100A/μs		0.81		μС

Notes

^{1.} Repetitive Rating: Pulse width limited by maximum junction temperature

^{2.} L = 1mH, I $_{AS}$ = 17A, V $_{DD}$ = 50V, R $_{G}$ = 25 Ω , Starting T $_{J}$ = 25 $^{\circ}$ C

^{3.} $I_{SD} \le$ 62A, di/dt \le 100A/ μ s, $V_{DD} \le$ BV $_{DSS}$, Starting T $_J$ = 25°C

^{4.} Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

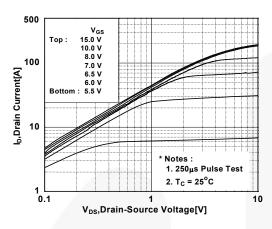


Figure 3. On-Resistance Variation vs. Drain
Current and Gate Voltage

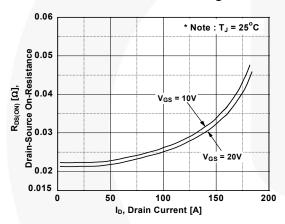


Figure 5. Capacitance Characteristics

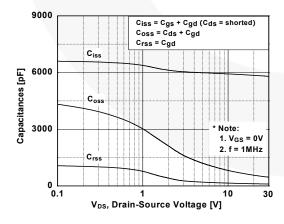


Figure 2. Transfer Characteristics

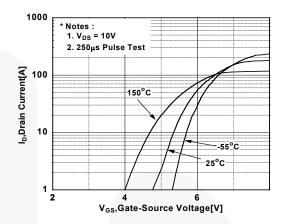


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

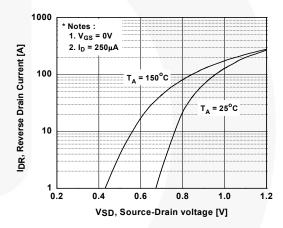
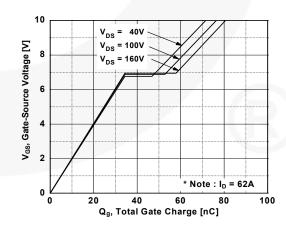


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. **Temperature**

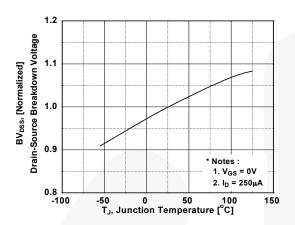


Figure 9. Maximum Safe Operating Area

perature 3.0 2.5

Figure 8. On-Resistance Variation vs. Tem-

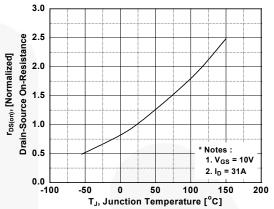
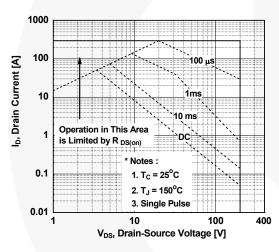


Figure 10. Maximum Drain Current vs. Case-**Temperature**



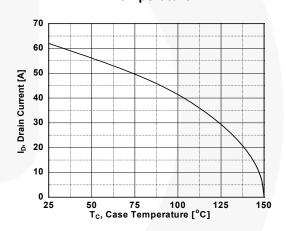


Figure 11. Transient Thermal Response Curve

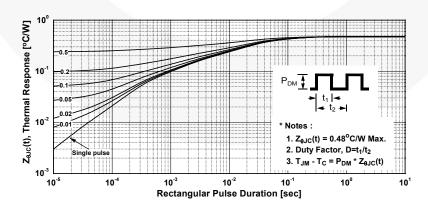


Figure 12. Gate Charge Test Circuit & Waveform

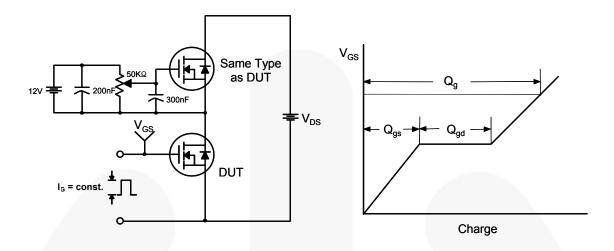


Figure 13. Resistive Switching Test Circuit & Waveforms

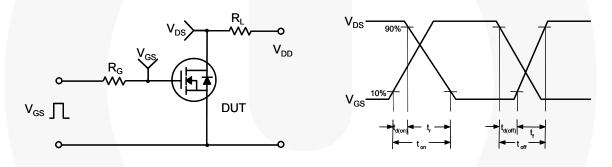
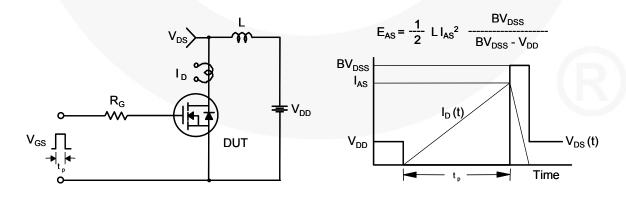
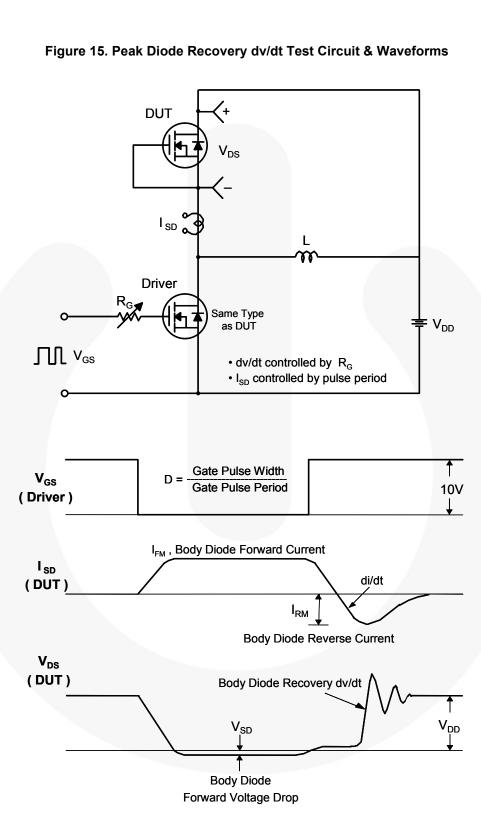


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms





Mechanical Dimensions

TO-263 2L (D²PAK)

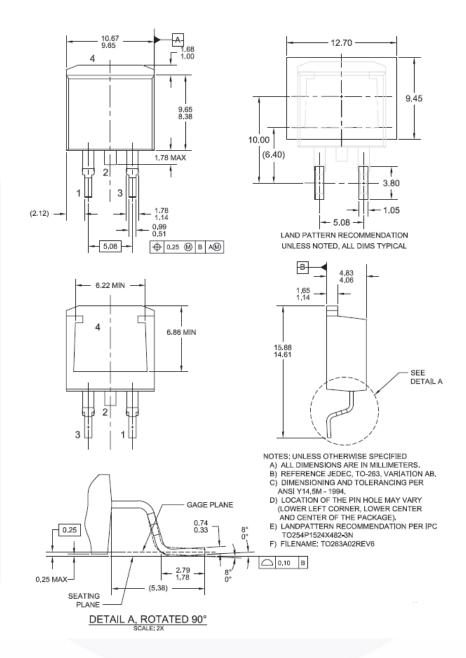


Figure 16. 2LD, TO263, Surface Mount

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Dimension in Millimeters





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